PRODUCT DATA SHEET

SP_1.0 THERMAL CONDUCTIVITY SOFT SILICON PAD

Last update:12.03.2021r.

This products possess good thermal conductivity and filling properties, softness and elastic characteristics can fill in the air gaps well between hot components and the heat sinks, the metal body and chassis, heat dissipation quickly, promote the work efficiency and extend the service life of equipment.

TECHNICAL CHARACTERISTICS		
Release liner	0,075 PET/0,2 [mm] blue film	
Colour	grey	
TECHNICAL FEATURES		**TEST METHOD**
Thickness	0,3 - 15 [mm] +/- 10%	ASTM D374
Density	2,0 [g/cm³]	ASTM D792
Hardness	60 +/- 5 [Shore 00]	ASTM D2240
Thermal conductivity	1,0 [W/m*K]	ASTM D5470
Thermogravimetric loss	<1,0 [%]	120°C/24hr
Surface resistance	>1,0 *10¹⁴ [Ω]	ASTM D257
Volume resistivity	>1,0 *10¹⁴ [Ω·cm]	ASTM D257
Dielectric strength	>6 [kV/mm]	ASTM D149
Use environment	-40 … +200 [°C]	-
Storage in a cool and dry place (below 25°C)	24 months	-
Size	200*400/ 200*20/ 200*50[mm]	-

Product feature

- Good thermal performance
- Soft and high compressibility, can be a vibration and shock absorber
- Self-adhesive
- Easy assembly
- Electrical insulation
- Provide a variety of thickness
- Halogen Free

Application area

- IC, CPU, graphics processing chip, power electronic capacitors, crystal.
- Diode lights, power supply module, server, the hard disk.
- Plasma displays, LCD monitor, PC, desktop computers, communications equipment, router.
- Memory module, video player, smart phone.

The above technical information is presented based on the average laboratory tests and can not be used as binding technical data for design purposes, they should not be used as a basis for granting the guarantee. The user is fully responsible for the decision to use the product and for its installation. Before using it is recommended to analyse the product features considering the type of combined materials, the state of its surface and application conditions.

INDUCOMP SP. Z O.O., ul. Ks. Jeremiego 62, 05-080 Izabelin
biuro@inducomp.pl; www.inducomp.pl